

ASML 2011 Third Quarter Results
Confirming expectation for record sales year

Oct 12, 2011

Safe Harbor

"Safe Harbor" Statement under the US Private Securities Litigation Reform Act of 1995: the matters discussed in this document may include forward-looking statements, including statements made about our outlook, realization of systems backlog, IC unit demand, financial results, average selling price, gross margin and expenses, dividend policy and intention to repurchase shares.

These forward looking statements are subject to risks and uncertainties including, but not limited to: economic conditions, product demand and semiconductor equipment industry capacity, worldwide demand and manufacturing capacity utilization for semiconductors (the principal product of our customer base), including the impact of general economic conditions on consumer confidence and demand for our customers' products, competitive products and pricing, the impact of manufacturing efficiencies and capacity constraints, the pace of new product development and customer acceptance of new products, our ability to enforce patents and protect intellectual property rights, the risk of intellectual property litigation, availability of raw materials and critical manufacturing equipment, trade environment, changes in exchange rates, available cash, distributable reserves for dividend payments and share repurchases, and other risks indicated in the risk factors included in ASML's Annual Report on Form 20-F and other filings with the US Securities and Exchange Commission.



Agenda

- Business summary
- Market
- ASML business update
- Outlook and summary



Business summary



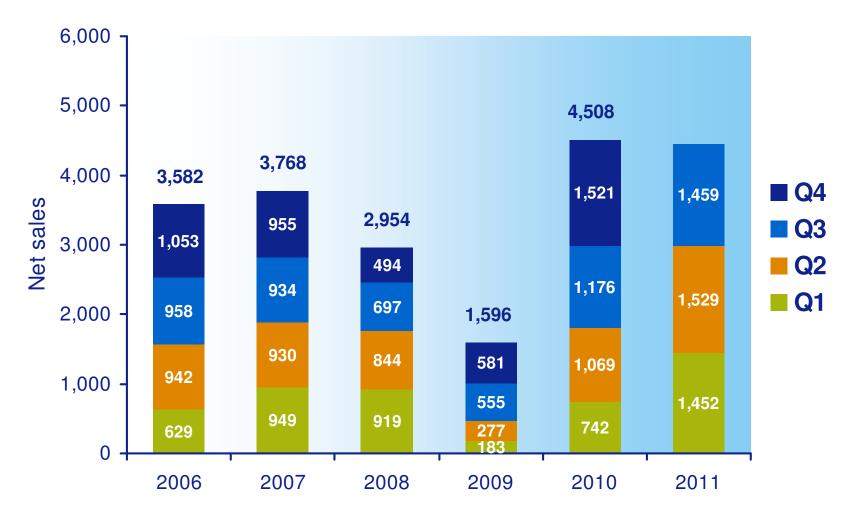
Q3 results - highlights

- Net sales of € 1,459 million, 55 systems sold valued at
 € 1,274 million, service and field option sales at € 185 million
- Gross margin of 42.1%
- Operating margin of 27.9%
- Net bookings are valued at € 514 million, 23 systems
- Backlog at € 1,994 million, 74 systems, excluding EUV (ASP new tools € 31.5 million)
- Generated € 338 million cash from operations

Net bookings and backlog numbers are excluding EUV.

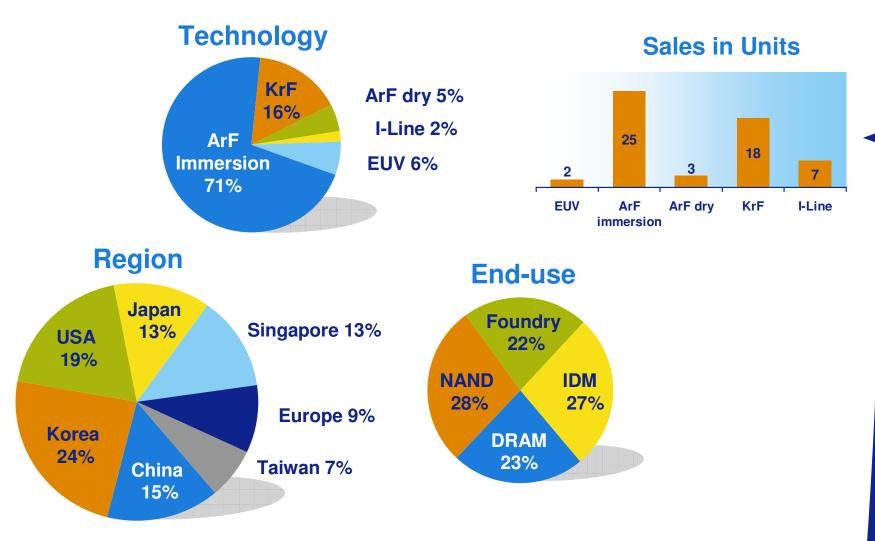


Total net sales M€





Net system sales breakdown in value: Q3 2011







Consolidated statements of operations M€

	Q2 11	Q3 11	
Net sales	1,529	1,459	
Gross profit Gross margin %	690 45.1%	613 42.1%	
R&D costs	145	150	
SG&A costs	51	56	
Income from operations Operating income %	494 32.3%	407 27.9%	
Net income Net income as a % of sales	432 28.3%	355 24.4%	
Earnings per share (basic) €	1.01	0.84	



Key financial trends 2010 – 2011

Consolidated statements of operations M€

	Q3 10	Q4 10	Q1 11	Q2 11	Q3 11	
Net Sales	1,176	1,521	1,452	1,529	1,459	
Gross profit Gross margin %	513 43.6%	685 45.0%	649 44.7%	690 45.1%	613 42.1%	-
R&D costs	137	141	145	145	150	
SG&A costs	48	50	54	51	56	
Income from operations Operating income %	328 27.9%	494 32.4%	450 31.0%	494 32.3%	407 27.9%	
Net income as a % of net sales	269 22.8%	407 26.7%	395 27.2%	432 28.3%	355 24.4%	
Units sold	51	69	63	63	55	
ASP new systems	24.1	22.4	22.5	22.7	27.1	
Net bookings value	1,391	2,315	845	840	514	



Cash flows M€

	Q2 11	Q3 11	
Net income	432	355	
Adjustments to reconcile net income to net cash flows from operating activities;			
Impairment and obsolescence	14	23	
Depreciation and amortization	43	43	
Deferred income taxes	(8)	(4)	
Other non-cash items	3	4	
Change in assets and liabilities	15	(83)	
Net cash provided by operating activities	499	338	
Net cash used in investing activities	(60)	(80)	
Net cash used in financing activities	(394)	(172)	
Total FX effects	(2)	10	
Net increase in cash and cash equivalents	43	96	



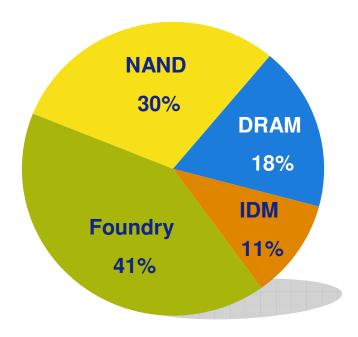
Balance sheets M€

Assets	Jui	n 2011	Sep	2011
Cash and cash equivalents	2,742	39%	2,838	40%
Accounts receivable, net	895	12%	812	11%
Finance receivables, net	62	1%	116	2%
Inventories, net	1,610	23%	1,456	20%
Other assets	468	7%	498	7%
Tax assets	195	3%	179	3%
Fixed assets	1,104	15%	1,209	17%
Total assets	7,076	100%	7,108	100%
iabilities and shareholders' equity	Jui	n 2011	Sep	2011
Current liabilities	2,230	31%	2,031	29%
Non-current liabilities	1,737	25%	1,793	25%
Shareholders' equity	3,109	44%	3,284	46%
liabilities and shareholders' equity	7,076	100%	7,108	100%



Bookings activity by sector - total value M€ 514

Bookings in value

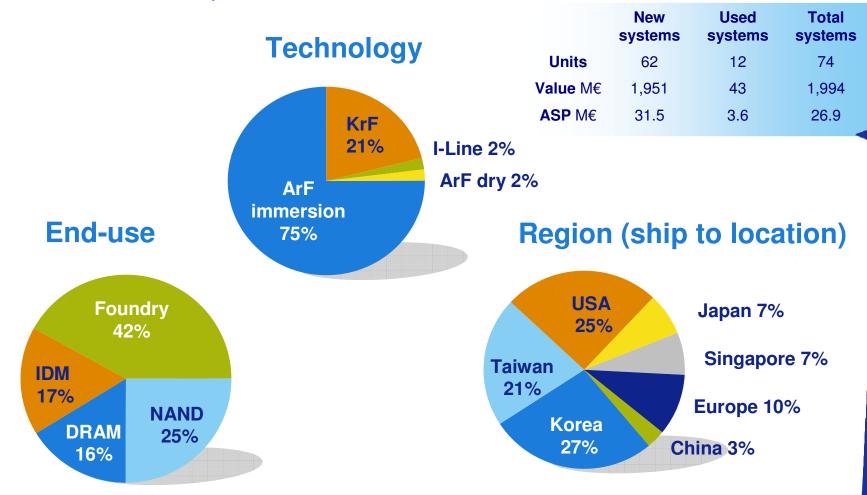


• Booked 21 new tools at € 506 million, 2 used at € 8 million



Backlog in value per Sep 25, 2011

Total value M€ 1,994



• 82% of backlog carry shipment dates in the next 6 months



Market **ASML**

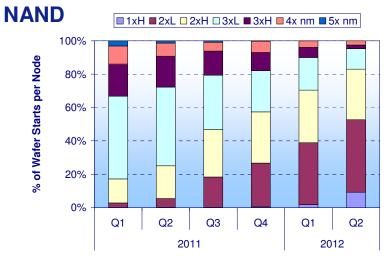
/ Slide 14

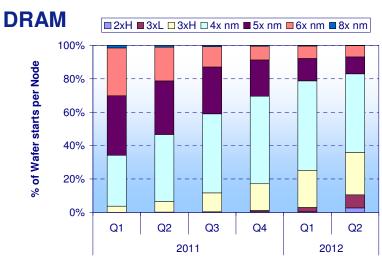
Business environment

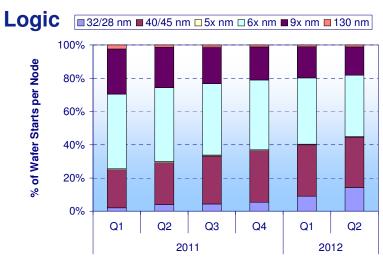
- Its is too early to understand how overall demand for semiconductor will drive ASML's business in 2012
- Sustained need for litho tools capable of printing new nodes will justify increased systems bookings in Q4 compared with Q3
- This level of bookings will start to support
 - continued technology upgrades for sub 20 nm nodes development
 - ramping production of advanced 2x nm nodes in Logic and NAND and 3x nm in DRAM

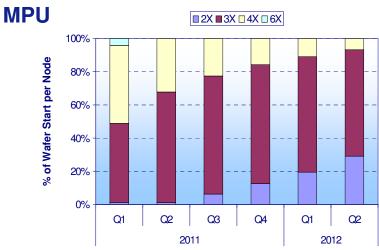


Rapid technology transitions being executed in each sector







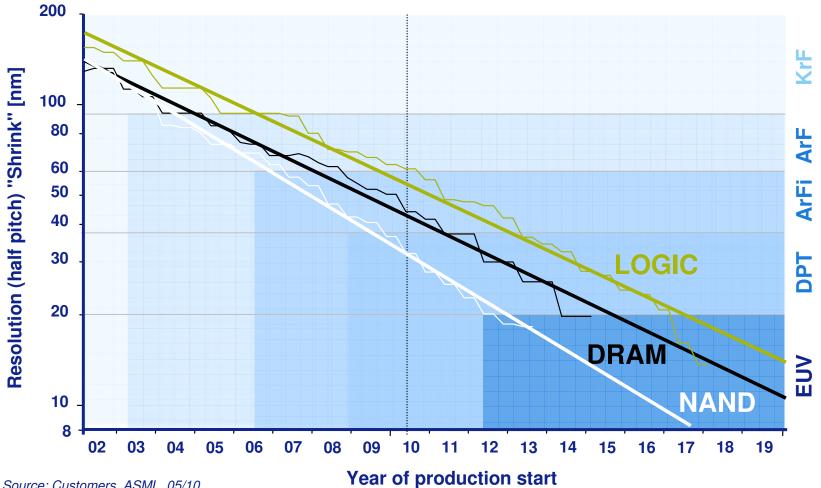




ASML business update



Options for shrink: Immersion and EUV



Source: Customers, ASML, 05/10

Notes:

- 1. R&D solution required 1.5~ 2 yrs ahead of Production
- 2. EUV resolution requires 7nm diffusion length resist
- 3. DPT = Double Patterning

/ Slide 18



ASML Dual Product Strategy enables continued shrink

Strong NXT platform roadmap optimized for multi pass patterning processes

Introduce EUV platform for volume manufacturing of critical layers





Concurrent development programs to enhance imaging, overlay, productivity and process control on both platforms



Q3 immersion platform highlights

- ASML's TWINSCAN NXT:1950
 reached milestone of more than 100
 shipments to date; total installed base
 of ASML immersion systems exceeds
 320 tools
- First TWINSCAN NXT:1950 with productivity of 200 wafers per hour (at 125 shots) is currently shipping



 TWINSCAN NXT:1950 surpassed the productivity milestone of more than 4000 wafers in a single day at a customer production site



EUV is making significant progress NXE:3100

- 4 machines are printing wafers, 1 system is being installed, 6th system is shipping
- Imaging performance has been demonstrated down to 22 nanometer in a single exposure
- Total exposed wafers by customers almost doubled in Q3 to more than 2500 wafers allowing them to develop the next generation chip production processes





EUV productivity roadmap redefined

- Source suppliers have now demonstrated power levels that support mid teens wafers per hour productivity
- These upgrades will be field implemented starting Q4 2011
- High confidence in reaching commercial viable productivity levels in the summer of 2012 through:
 - pre-pulse for conversion efficiency increase
 - optimized filtering for higher EUV light transmission
 - duty cycle improvement for continuous production



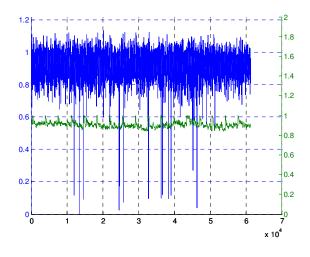
NXE Source power roadmap and current status

Q3 2011	Q4 2011	Q1 2012	Q2 2012	Q3 2012	Q4 2012
Power <10W					
		Power 20-50W			
				Power >100W	

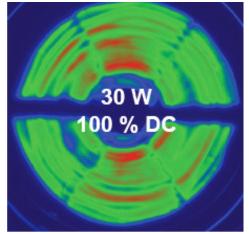
Demonstrated at supplier



Expose power 30W @ 80% duty cycle without pre-pulse









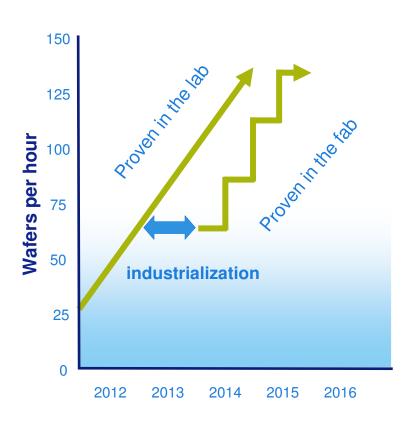
EUV transition

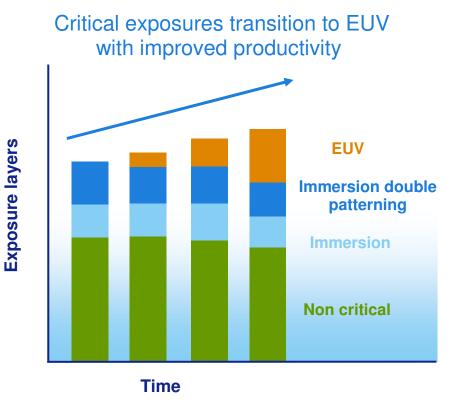
- EUV will be first introduced for layers that are difficult / expensive to print with multi pass immersion patterning
- Every customer, every application, every product and every layer will have its own difficulty / cost threshold
- Based upon economics and productivity more layers will be printed with EUV over time
- Therefore there will be a gradual transition to EUV

EUV simplifies process, reduces cost, improves yield and provide additional shrink opportunity



EUV industrialization in 2012 - 2014







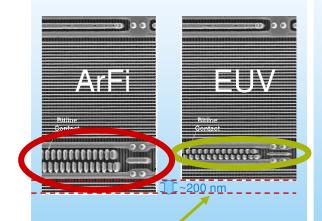
Additional EUV shrink benefits

Die size reduction & cost per wafer (CpW)

NAND

CpW Savings: up to 50 \$/wafer

Case: Bit Line Contacts



Savings:

~4% in die size

Additional savings:

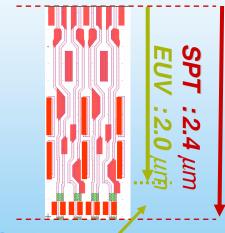
Cycle time / Yield

Source: ASML Strategic Marketing
/ Slide 26

DRAM

CpW Savings: up to 100 \$/wafer

Case: Sense Amplifiers



Savings:

~5% in die size

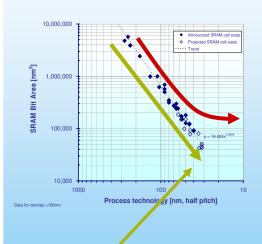
Additional savings:

Cycle time / Yield / Product design flexibility

Logic

CpW Savings: up to 400 \$/wafer

Case: SRAM 14nm shrink



Savings:

~7% in die size

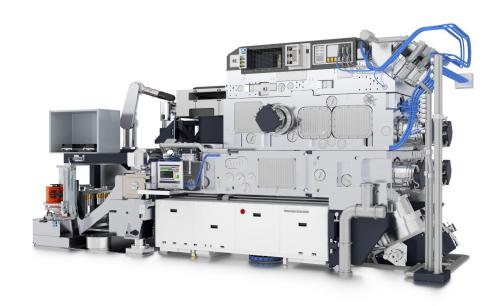
Additional savings:

Cycle time / Yield / Product design flexibility



EUV NXE:3300 – Volume manufacturing tool

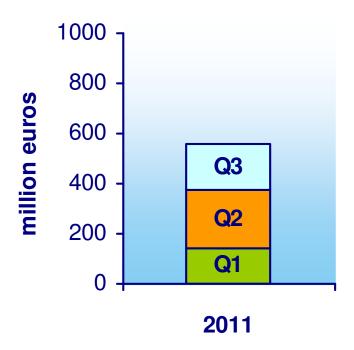
 Assembly and integration of the first NXE:3300 has started for first delivery in H2 2012





Share buy back program

- € 1 billion, 24 month share buy back program
 - 56% of program executed
 - 20.7 million shares repurchased at an average price of € 26.98
 - weekly updates available on ASML's website





Outlook and summary



Q4 2011 outlook

- Bookings expected at a level above Q3
- Net sales above € 1.1 billion including 1 EUV system (€ 40 million at 0% gross margin)
- Gross margin about 41%
- R&D costs at € 150 million
- SG&A costs at € 56 million

 ASML expects full year 2011 sales to hit a record level of about EUR 5.5 billion



